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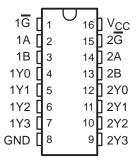
- Designed Specifically for High-Speed Memory Decoders and Data Transmission Systems
- Incorporate Two Enable Inputs to Simplify Cascading and/or Data Reception
- Package Options Include Plastic Small-Outline (D), Thin Shrink
 Small-Outline (PW), and Ceramic Flat (W)
 Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J)
 300-mil DIPs

description

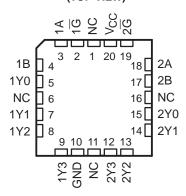
The 'HC139 are designed for high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay time of these decoders and the enable time of the memory are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

The 'HC139 comprise two individual 2-line to 4-line decoders in a single package. The active-low enable (\overline{G}) input can be used as a data line in demultiplexing applications. These decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit.

SN54HC139 . . . J OR W PACKAGE SN74HC139 . . . D, N, OR PW PACKAGE (TOP VIEW)



SN54HC139 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54HC139 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74HC139 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

	INPUTS			OUTPUTS						
_	SEL	ECT	0011013							
G	В	Α	Y0	Y1	Y2	Y3				
Н	Х	Х	Н	Н	Н	Н				
L	L	L	L	Н	Н	Н				
L	L	Н	Н	L	Н	Н				
L	Н	L	Н	Н	L	Н				
L	Н	Н	Н	Н	Н	L				

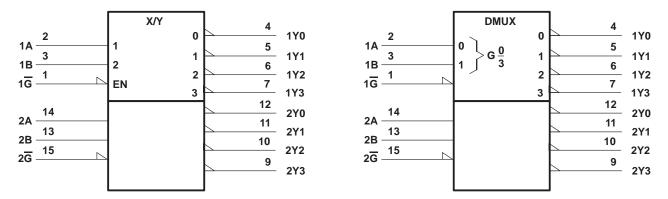


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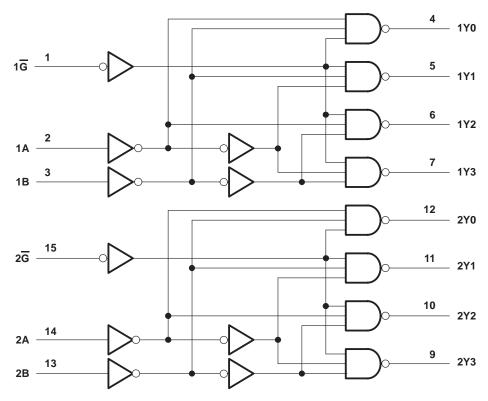
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logic symbols (alternatives)†



 $[\]dagger$ These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, PW, and W packages.

SN54HC139, SN74HC139 DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

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absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V _{CC}			–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)		±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_O$	CC) (see Note 1))	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CO}	;)		±25 mA
Continuous current through V _{CC} or GND			±50 mA
Package thermal impedance, θ_{JA} (see Note 2	2): D package .		113°C/W
	N package .		78°C/W
	PW package		149°C/W
Storage temperature range, T _{stg}			–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

			SI	SN54HC139			SN74HC139		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vсс	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			V
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
	Low-level input voltage	V _{CC} = 2 V	0		0.5	0		0.5	
VIL		V _{CC} = 4.5 V	0		1.35	0		1.35	V
		V _{CC} = 6 V	0		1.8	0		1.8	
٧ı	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
	Input transition (rise and fall) time	V _{CC} = 2 V	0		1000	0		1000	
t _t		V _{CC} = 4.5 V	0		500	0		500	ns
		V _{CC} = 6 V	0		400	0		400	
TA	Operating free-air temperature		-55		125	-40		85	°C

SN54HC139, SN74HC139 DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vaa	Т	A = 25°C	;	SN54H	C139	SN74H	C139	UNIT
PARAMETER	1251 CC	MUITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		٧
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
	V_{OL} $V_{I} = V_{IH} \text{ or } V_{IL}$ I_{OI}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	
			4.5 V		0.001	0.1		0.1		0.1	
VOL			6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160		80	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

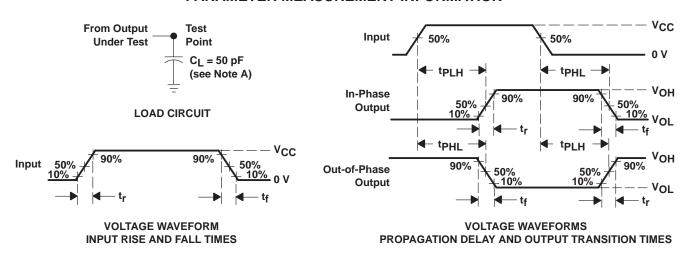
PARAMETER	FROM	TO (OUTPUT)	Vaa	T,	_Δ = 25°C	;	SN54F	IC139	SN74H	C139	UNIT
PARAMETER	(INPUT)		Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		Y	2 V		47	175		255		220	
	A or B		4.5 V		14	35		51		44	ns
.			6 V		12	30		44		38	
^t pd	G	Y	2 V		39	175		255		220	
			4.5 V		11	35		51		44	
			6 V		10	30		44		38	
		Y	2 V		38	75		110		95	
t _t			Υ	4.5 V		8	15		22		19
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per decoder	No load	25	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

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